

# DCR5890H52



# **Phase Control Thyristor**

**Preliminary Information** 

DS6159-1 September 2014 (LN31987)

### **FEATURES**

- Double Side Cooling
- High Surge Capability

### **APPLICATIONS**

- High Power Drives
- High Voltage Power Supplies
- Static Switches

#### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages V <sub>DRM</sub> and V <sub>RRM</sub> V	Conditions		
DCR5890H52* DCR5890H50 DCR5890H48	5200 5000 4800	$\begin{array}{l} T_{vj} = -40^{\circ}C \ to \ 125^{\circ}C, \\ I_{DRM} = I_{RRM} = 600 mA, \\ V_{DRM}, \ V_{RRM} \ t_p = 10 ms, \\ V_{DSM} \& \ V_{RSM} = \\ V_{DRM} \& \ V_{RRM} \ + 100 V \\ respectively \end{array}$		

Lower voltage grades available. \*5000V @  $-40^{\circ}$ C, 5200V @  $0^{\circ}$ C

#### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

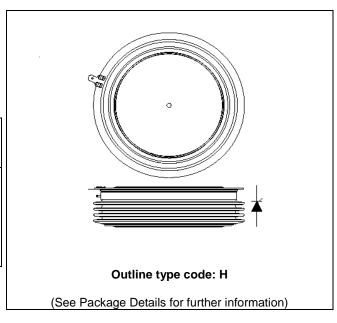
#### DCR5890H52

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

### **KEY PARAMETERS**

200V
890A
6970A
2000V/µs
00A/µs

#### \* Higher dV/dt selections available



#### Fig. 1 Package outline





### **CURRENT RATINGS**

 $T_{case} = 60^{\circ}C$  unless stated otherwise

Symbol	Parameter	meter Test Conditions		Units
Double Sid	Double Side Cooled			
I <sub>T(AV)</sub>	Mean on-state current	Half wave resistive load	5890	А
I <sub>T(RMS)</sub>	RMS value	-	9250	А
Ι <sub>Τ</sub>	Continuous (direct) on-state current	-	8030	А

### SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>TSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}C$	86.97	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 0$	37.8	MA <sup>2</sup> s

### THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.004255	°C/W
		Single side cooled	Anode DC	-	0.008	°C/W
			Cathode DC	-	0.0093	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Clamping force 135.0kN	Double side	-	0.0009	°C/W
		(with mounting compound)	Single side	-	0.0018	°C/W
$T_{vj}$	Virtual junction temperature	Blocking V <sub>DRM</sub> / V <sub>RRM</sub>		-	125	°C
T <sub>stg</sub>	Storage temperature range			-55	125	°C
Fm	Clamping force			120	155	kN





# **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 125°C		-	600	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V <sub>DRM</sub> , T <sub>j</sub> = 125°C, ga	ate open	-	2000	V/µs
dl/dt	Rate of rise of on-state current	From 67% $V_{\text{DRM}}$ to 2x $I_{\text{T(AV)}}$	Repetitive 50Hz	-	200	A/µs
		Gate source $30V$ , $10\Omega$ ,	Non-repetitive	-	500	A/µs
		t <sub>r</sub> < 0.5μs, Τ <sub>j</sub> = 125°C				
V <sub>T(TO)</sub>	Threshold voltage – Low level	500 to 4000A at $T_{case} = 125^{\circ}$	С	-	0.845	V
	Threshold voltage – High level	4000 to 8000A at $T_{case} = 125$	°C	-	1.15	V
r <sub>T</sub>	On-state slope resistance – Low level	500A to 4000A at $T_{case} = 125$	5°C	-	0.155	mΩ
	On-state slope resistance – High level	4000A to 8000A at T <sub>case</sub> = 125°C		-	0.093	mΩ
t <sub>gd</sub>	Delay time	$V_D = 67\% V_{DRM}$ , gate source 30V, 10 $\Omega$		-	3	μs
		$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	$I_T = 3000A, T_j = 125^{\circ}C,$ $V_R = 200V, dI/dt = 1A/\mu s,$			700	μs
		$dV_{DR}/dt = 20V/\mu s$ linear				
Qs	Stored charge	- I <sub>T</sub> = 3000A, T <sub>i</sub> = 125°C, dI/dt – 1A/µs,		3260	8185	μC
I <sub>RR</sub>	Reverse recovery current	$V_{\text{Rpeak}} \sim 3100 \text{V}, V_{\text{R}} \sim 2100 \text{V}$		45	77	A
IL	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	A
Iн	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 500A, I_T = 5A$		-	300	mA



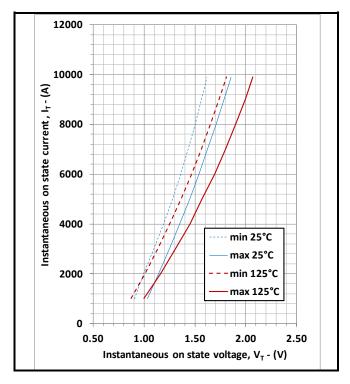
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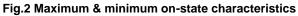


# GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V <sub>GT</sub>	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	1.5	V
$V_{GD}$	Gate non-trigger voltage	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	0.4	V
I <sub>GT</sub>	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	350	mA
I <sub>GD</sub>	Gate non-trigger current	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	10	mA

### **CURVES**



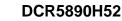


### **V<sub>TM</sub> EQUATION**

 $V_{TM} = A + Bln (I_T) + C.I_T + D.\sqrt{I_T}$ 

Where A = 2.0256  
B = -0.2916  
C = -0.00005  
D = 0.03214  
these values are valid for 
$$T_i = 125^{\circ}C$$
 for I<sub>T</sub> 500A to 8000A





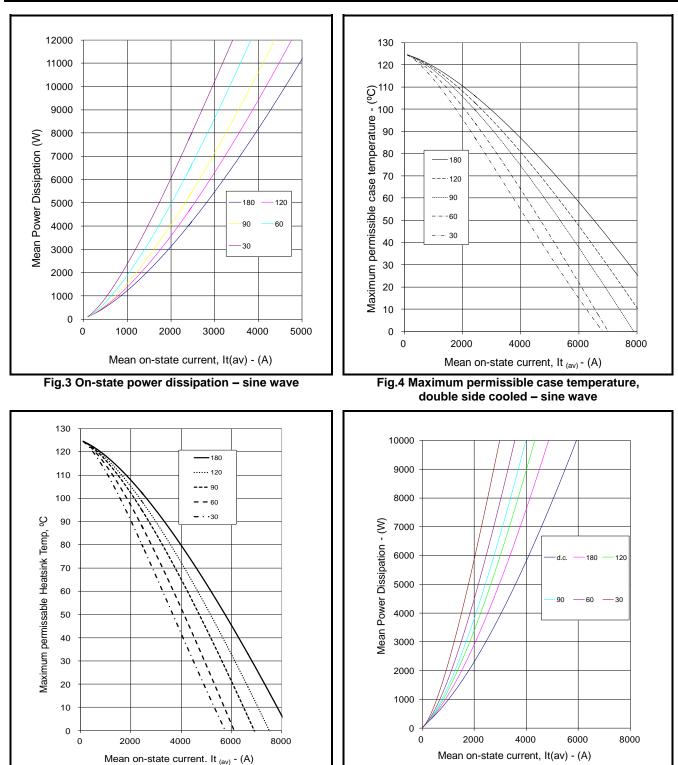
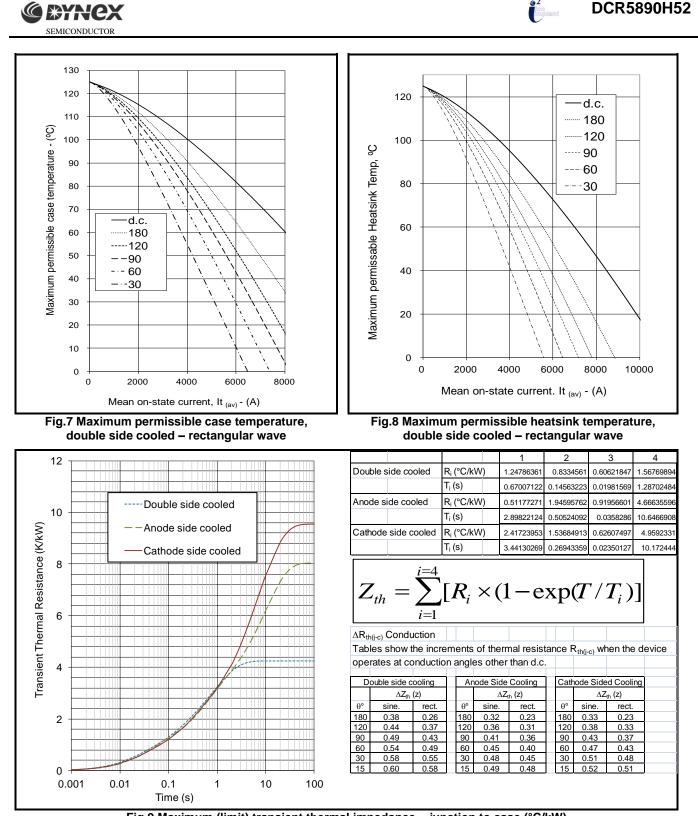
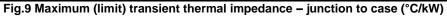


Fig.6 On-state power dissipation – rectangular wave

Fig.5 Maximum permissible heatsink temperature,

double side cooled - sine wave





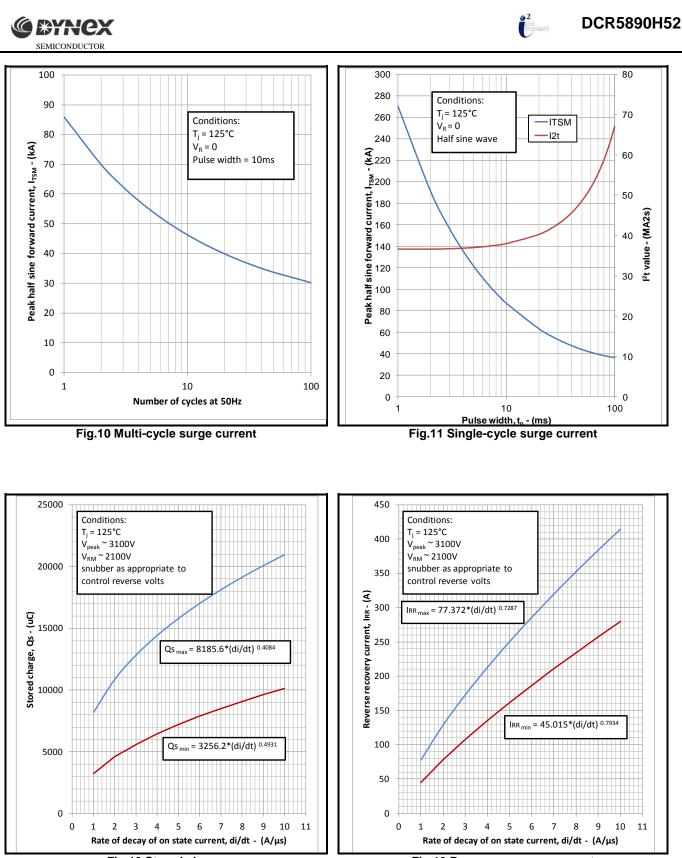
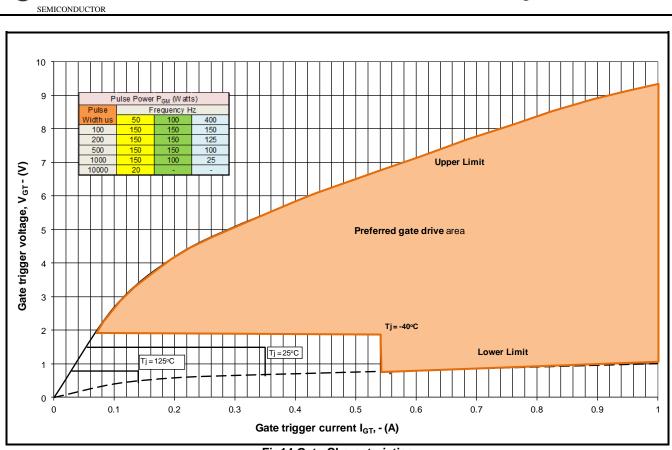


Fig.12 Stored charge

Fig.13 Reverse recovery current



@2 Implant DCR5890H52



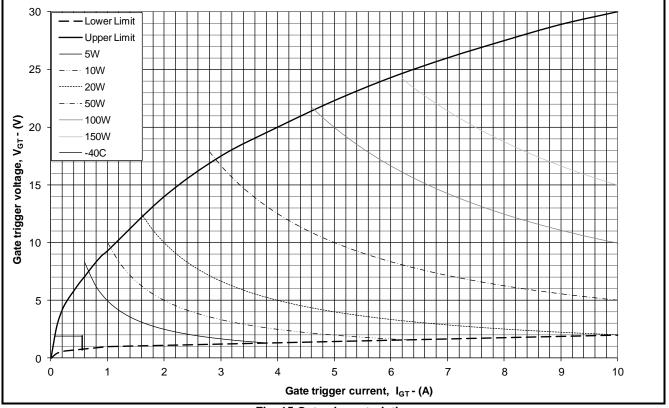


Fig. 15 Gate characteristics

@ BYNEX



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#### PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

	Maximum	Minimum Thickness	3rd angle projection · ⊕ · - ← DO NOT SCALE IF IN DOUBT ASK
Device	(mm)	(mm)	
DCRxxxxH42	35.15	34.28	HOLE Ø3.60 X 4.00 DEEP (N BOTH ELECTROBES)
DCR5890H52	35.27	34.4	LELUIRODES)
DCR4420H65	35.3	34.7	
DCR4660H65	35.3	34.7	20° OFFSET (NOMINAL) TO GATE TUBE
DCR3640H85	35.65	35.05	
DCR3980H85	35.65	35.05	
			Ø170±0.3 Ø115 NOM. GATE Ø115 NOM. Ø161 MAX.
			Lead length: 420mm Lead terminal connector: M4 ring
			Package outline type code:H

Fig.16 Package outline





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